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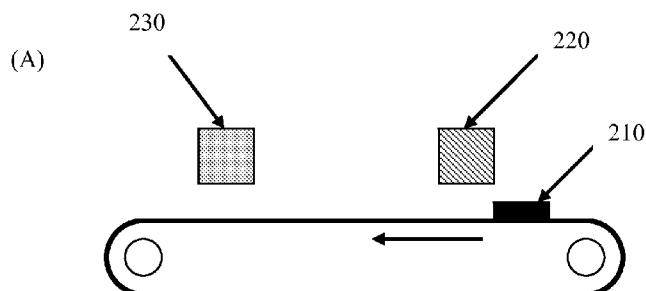


FIG. 2

(57) Abstract: A two-step pulse lamp sintering process using a series of low energy light pulses to pre-treat the target before applying one or more higher energy pulses to sinter the metallic nanoparticles. The pulses can be provided so that nanoparticles are not sintered by the low energy pulse(s), but are sintered by the high energy pulse(s).

